

ABSTRACT OF THE DISCLOSURE

Particles adhering to the surface of a substrate are removed by physical action of injection of droplets or megasonic vibrations or by combination of the physical action and slight etching on the surface of the substrate. On the other hand, metal contaminants
5 adhering to the surface of the substrate are altered to hydroxides with an alkaline solution and thereafter dissolved with an acid solution to be removed. Thus, it is possible to rapidly process the substrate while minimizing the quantity of etching on the surface of the substrate.